

Technical Data Sheet



THICK FILM MATERIALS

Product Type: Conductors Product Name: C5819

Gold Conductor Paste

Description

C5819 is a screen printable lead and cadmium free gold conductor, containing a mixed bonded Au formulation for Au and Al wire bonding.

Key Benefits

- Suitable for fine line printing
- Excellent Au and Al wire bondability and contact resistivity properties
- Free of lead, cadmium, nickel and phthalate

Typical Properties (Pastes)		
Form	Pseudoplastic paste	
Viscosity	15 – 55 Pas (25 °C, D = 75/s)	
Solids	88.0 % ± 1.5 %	
Printing Speed	Up to at least 10 cm/s	
Coverage	c. 53 cm²/g (FFT: 12 μm)	
Shelf Life	6 months from date of shipment with correct storage (in a dry, cool (5 – 25 °C) and dark place with container tightly shut).	

Processing

1) Spatulate well prior to processing.

When stored in a refrigerator, the paste should have acquired room temperature before being opened, to avoid condensation.

- 2) Print through a 200 325 mesh stainless steel screen.
- 3) Level at room temperature for 10 15 minutes.
- 4) Dry at 150 °C for 10 20 minutes.
- 5) Fire at 850 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30 - 60 minutes.

Typical Properties (Fired) ¹			
Fired Film Thickness ² (FFT)	6 – 11 j	μm	
Line Definition	≥ 100 / 100 (width / space)		
Resistivity ²	$\leq 6.5~\text{m}\Omega/\Box$ (FFT: 10 μm)		
Al Wire Bondability³ 32 μm AlSi Wire 150 μm Al Wire	Initial Initial	> 45 cN > 250 cN	
Au Wire Bondability ³ 30 µm Au Wire 60 µm Au Wire	Initial Initial		

Note: Bond shear test made on alumina

Thinner

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Legend:

¹⁾ Typical property based on laboratory test methods. For optimum results all materials should be fired in a profiled furnace supplied with dried, hydrocarbon and other contaminant free air (PP-1).

 $^{2)}$ Measured after printing with a 325 mesh steel screen; thickness of screen and emulsion combined was c. 75 μm , and the resultant printed track was 500 μm wide.

³⁾ Au wire bonded with a Hughes TSB 460 in Heraeus' labs; other values may depend on various parameters e.g. the bonder, the bonding speed, the wire, the loop lengths, employed etc.

* See the data sheet issue date (DD/MM/YY) as reference of validity of latest edition which is available on request

Heraeus Electronics Heraeus Deutschland GmbH & Co. KG Heraeusstraße 12 – 14

63450 Hanau, Germany www.heraeus-electronics.com Americas

Phone +1 610 825 6050 electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649 electronics.apac@heraeus.com

China

Phone +86 53 5815 9601 electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370 electronics.emea@heraeus.com

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